







Copyright

D

(2) SOLDER BALLS WILL NOT BE PERFECT SHPERICAL SHAPE DUE TO REFLOW ATTACHMENT.

(3) mated height effected by customers? PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE & SOLDER PASTÉ.

(4) CONTACTS IN ROWS A,C,E,G,J,K,M,P,R AND T ARE SINGLE BEAM CONTACTS USED AS GROUND PINS. (NOTE: CONTACTS IN ROWS J & K ARE TIED TOGETHER [COMMONED])

(5) CONTACTS IN ROWS B,D,F,H,L,N,Q AND S ARE DUAL BEAM CONTACTS, TYPICALLY USED AS SIGNAL PINS.

REV F - 2006-04-17

FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033. LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEADFREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION.

(8)	THIS PRODUCT MEETS THE EUROPEAN UNION
<u>(,</u>	DIRECTIVES AND OTHER COUNTRY
	REGULATIONS AS DESCRIBED IN GS-22-008.
	PRODUCT MEETING THIS DIRECTIVE IS
	INDENTIFIED IN THE CODE NUMBER
	MARKED ON EACH PART BY HAVING
	AN "X" IN THE SEVENTH CHARACTER
	POSTION.

DIM. "A"	PLUG ASSEMBLY P/N
25	55720
27	10026804
28	10055143
30	55700
35	55727
40	10054784

С.

Rev GIG-Array I5mm RECEPTACLE 10060913 ASSY, 296 SIG. POS catalog no CUSTOMER sheet 4 of 4

PDM: Rev:B